

MEG – I65 Epoxy

CHEMICAL PRODUCT

PRODUCT NAME: MEG-I65

COLOR: White

CHEMICAL FAMILY: Mixture

MOLECULAR FORMULA: Mixture

MOLECULAR WGT: Mixture

GLASS TRANSITION TEMP: 50 °C

THICKNESS: 0.001" or 0.003" \pm 0.0005" (25 μ m or 76 μ m)

CURE TEMP: 177 °C for 1 hour

C.T.E.: 13×10^{-6} /°C

ELECTRICAL INSULATOR

PRODUCT FEATURES

- ▶ Excellent adhesion to metal, glass and ceramics.
- ▶ No primer required.
- ▶ At temperatures \leq 25 °C, epoxy has little tackiness.
- ▶ Low flow upon curing; optimal for flat sealing surfaces.

STORAGE

Store in a refrigerator at 32°F to 35°F (0°C to 2°C) or in a freezer between 15°F and 32°F (-9 to 0°C).

Allow the epoxy to regain room temperature just prior to use. Stored under these conditions, the shelf life of the epoxy is approximately 6 – 10 months.

CURING SCHEDULE

Allow epoxy to warm up to room temperature before placing on the surface to be sealed. Curing time is a function of temperature, but a cycle of 60 minutes at 177°C under 20 – 30 psi (0.14 to 0.21 MPa) can be used as a reference. An alternative curing cycle is 204 C for 15 minutes at the same pressure. However, bonding conditions can vary considerably with satisfactory results, using heat-up interval of 1 – 30 minutes (depending on size) and curing temperatures from 177°C to 204°C. Preheated convections ovens are recommended. Cure Atmosphere: air, nitrogen or vacuum.

Bonding conditions are optimized when the epoxy is fresh. The sealing surface should be dry and free of large particles, debris, oils and other foreign material.